

# PCB VERIFICATION AND ORDERING

George Hadley ©2016, Images Property of their Respective Owners.

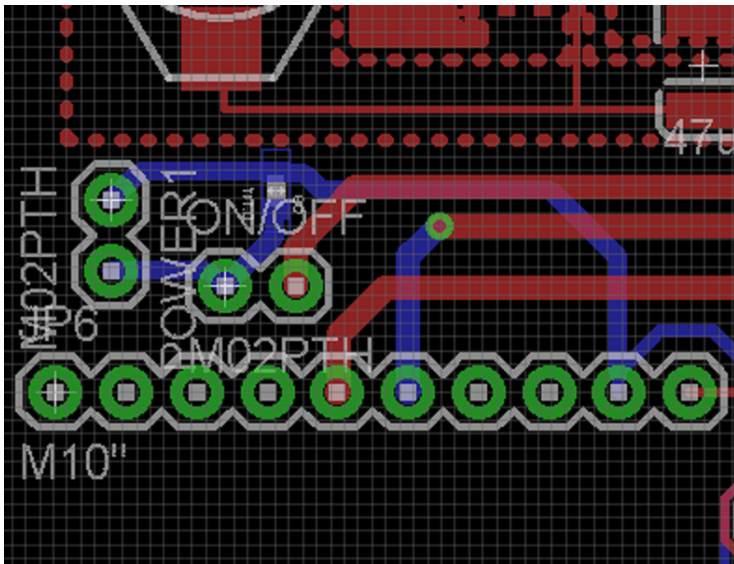
# OUTLINE

- PCB Verification
  - Parts Completion Check
  - Footprint Verification Check
  - Parts Placement Check
  - Space Conflicts Check
  - Routing Minimization Check
  - Signal Plane Check
  - Silkscreen Check
- Gerber File Generation
- PCB Ordering

# PARTS COMPLETION CHECK

## Values and Ratings of Passive Components

- When choosing passive components, both component value and power/voltage ratings matter
- Consider: How much current is running through your resistors? How much voltage is being dropped across your capacitors?



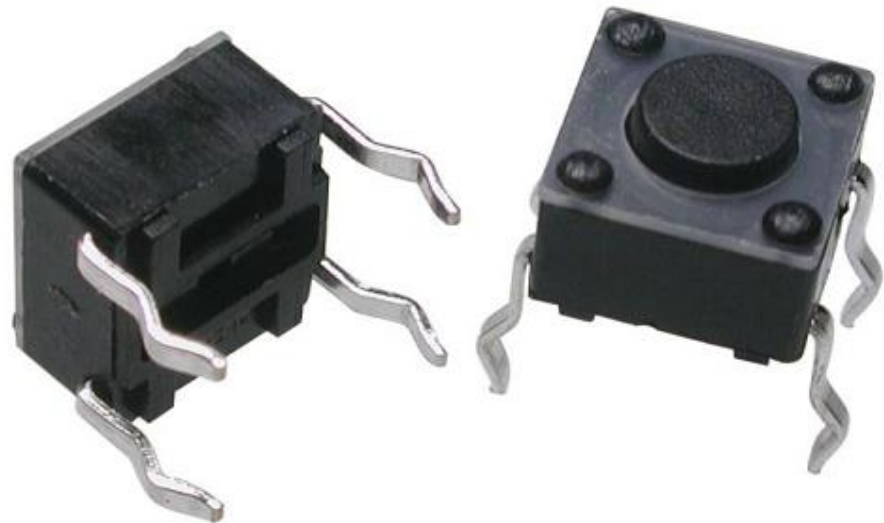
Which of these resistor packages is more likely to survive having 4 amps run through it?



# PARTS COMPLETION CHECK

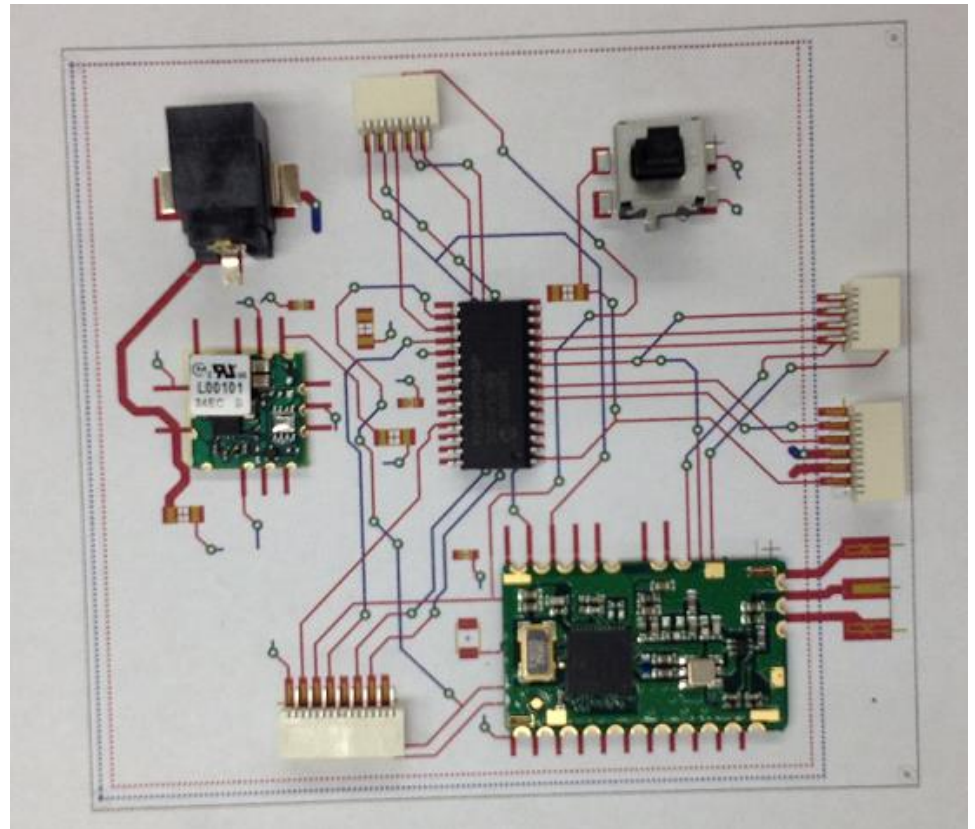
## Miscellaneous PCB Components

- Does your board have...
  - A programming header? (note: use of an RJ-11 connector is not required)
  - Reset tactile switch? (tact switches are recommended over pushbuttons and other button types)
  - A power connector and LED?
  - Mounting holes?
  - Debugging support?



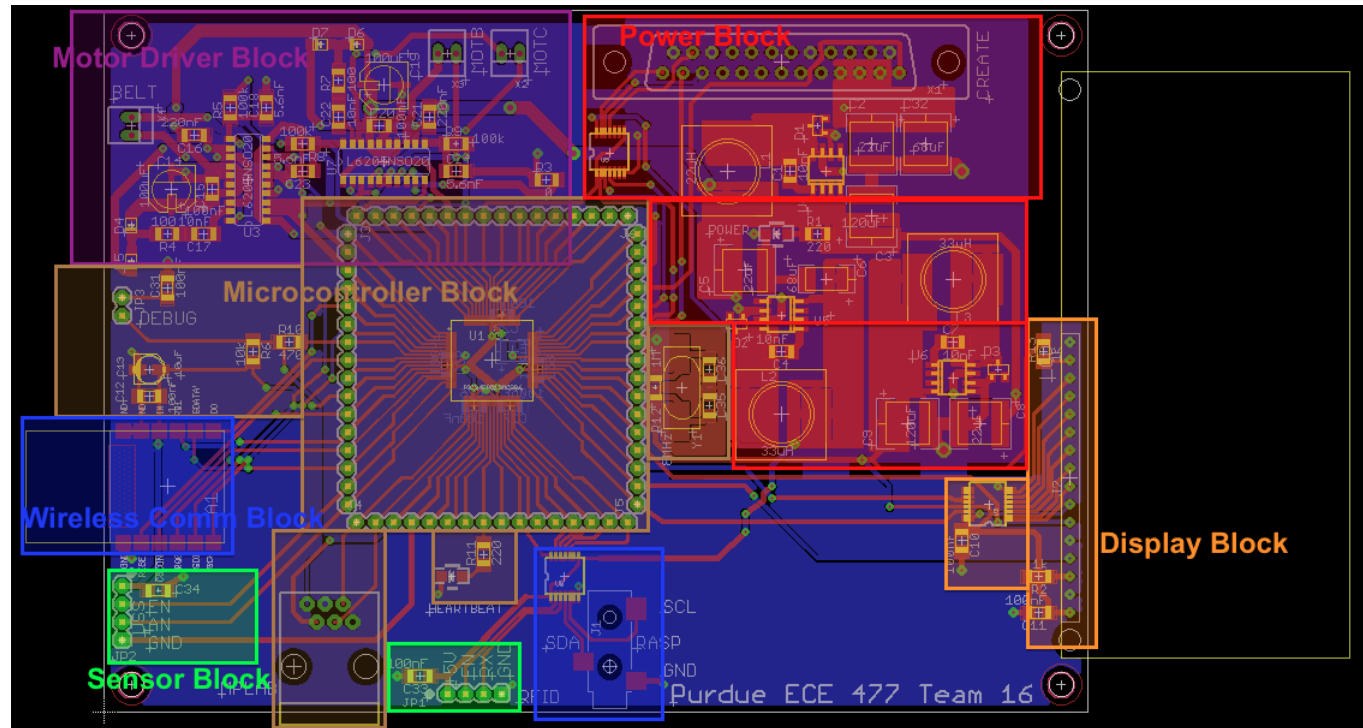
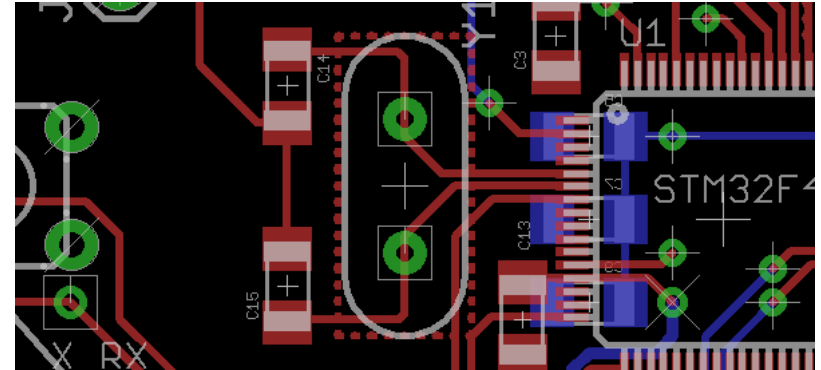
# FOOTPRINT VERIFICATION CHECK

- Print a 1:1 scale layout of your board and lay your parts on the printout to ensure that layout footprints match the actual component packages
- Board doesn't have to be fully routed; what matters is that you have at least 1 instance of every unique PCB footprint on the printout to compare against physical parts



# PARTS PLACEMENT CHECK

- Is your crystal physically close to your microcontroller?
- Are decoupling capacitors near/under microcontroller?
- Have connectors been placed at board edges?
- Are parts grouped by system or a logical order that minimizes trace lengths?

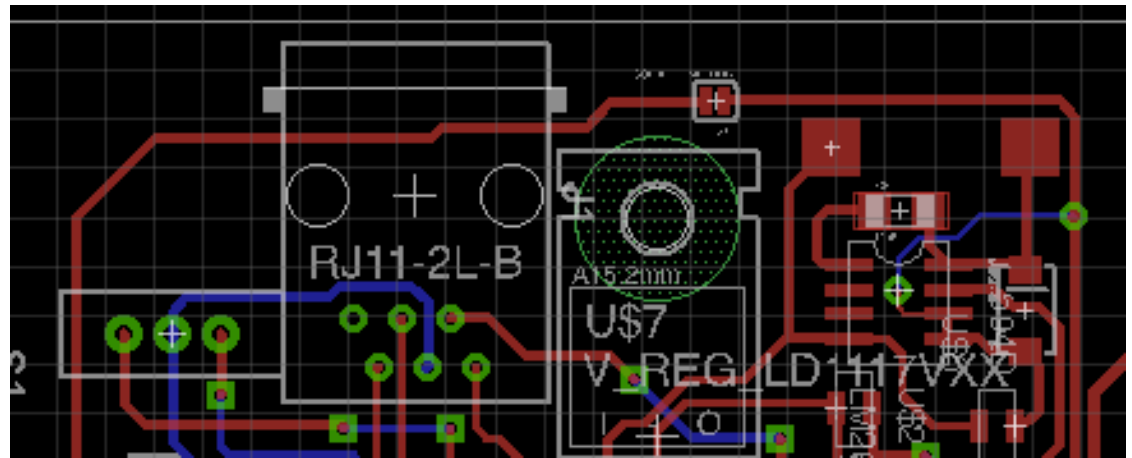
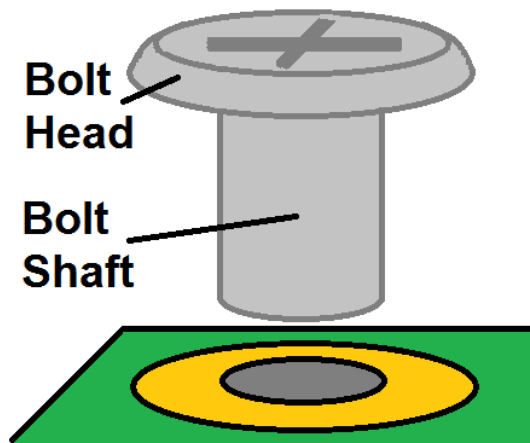




# MECHANICAL CHECK

## X/Y-Space Conflicts

- Will your parts sit flush with the board? Has clearance been provided for the X/Y space around your parts?
- For your mounting holes, has clearance been provided for the heads of the bolts in addition to the bolt shaft?
- Best remedy to avoid these types of conflicts is to place an outline of the part in the documentation layer



# MECHANICAL CHECK

## Z-Space Conflicts

---

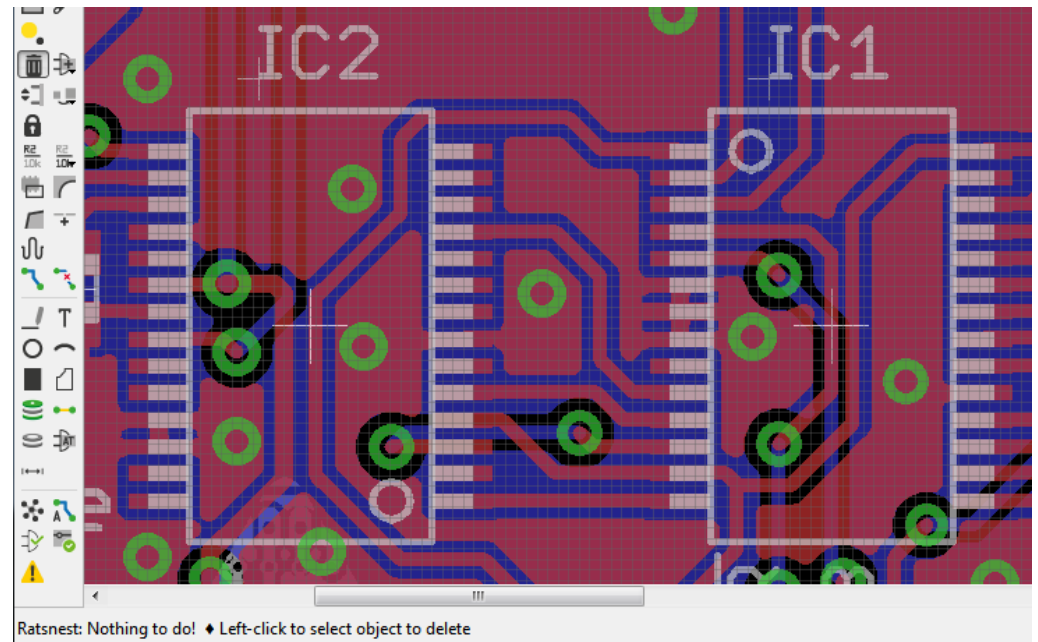
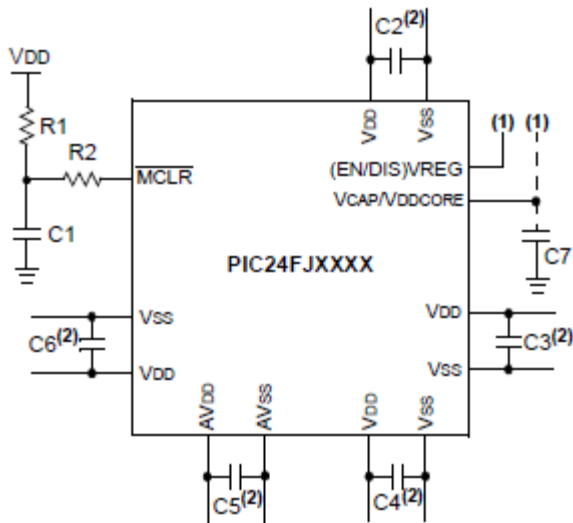
- When students add breakout boards, RPis/Atom Boards, utilize stacked PCB design, or have special packaging constraints, the height of components becomes important. If components are too tall, they may run into and/or create a short circuit with another board
- Best remedy to avoid these types of conflicts is to place an outline of the part in the documentation layer (so you know when to check for height concerns)



# ROUTING CHECKS

## Routing Completion Check

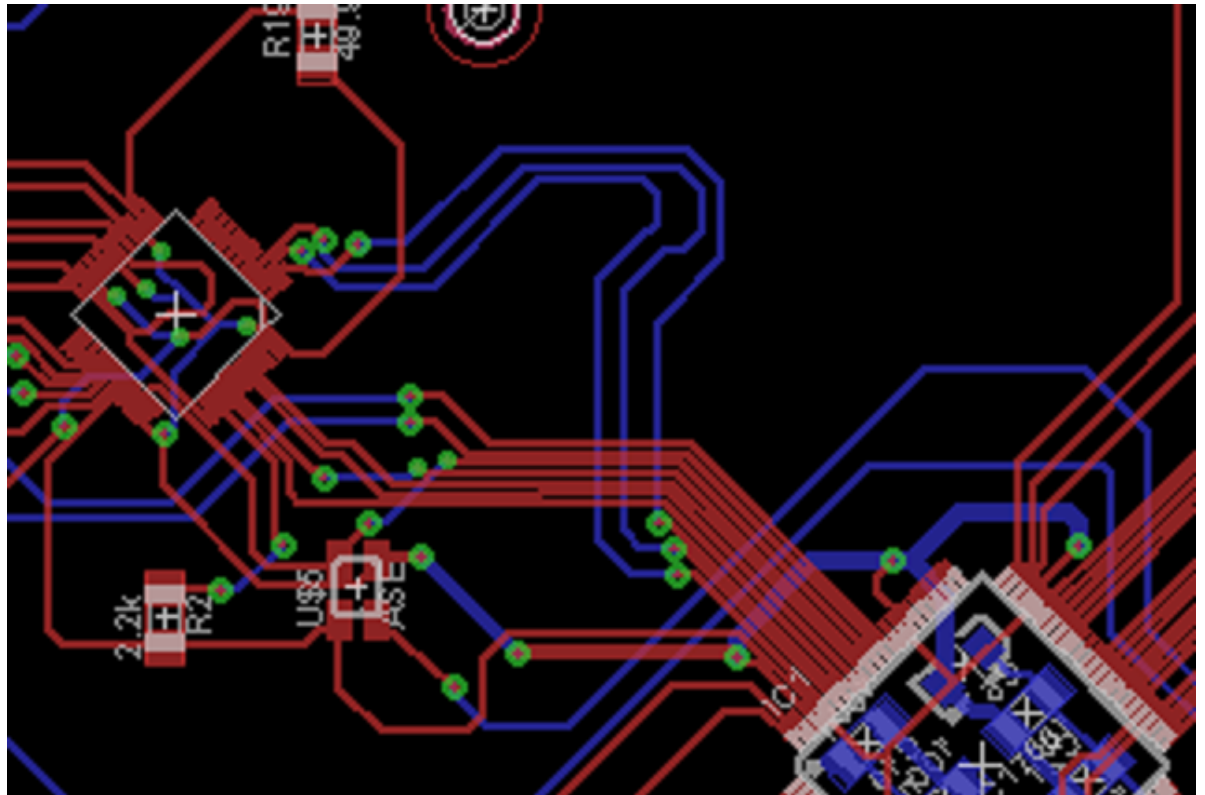
- Have all airwires been resolved? (In Eagle, the ratsnest command should report “Nothing to Do”)
- Have you separated AGND from GND using a jumper, SMD resistor, or as suggested in your microcontroller connection guidelines?



# ROUTING CHECKS

## Trace Length Minimization Check

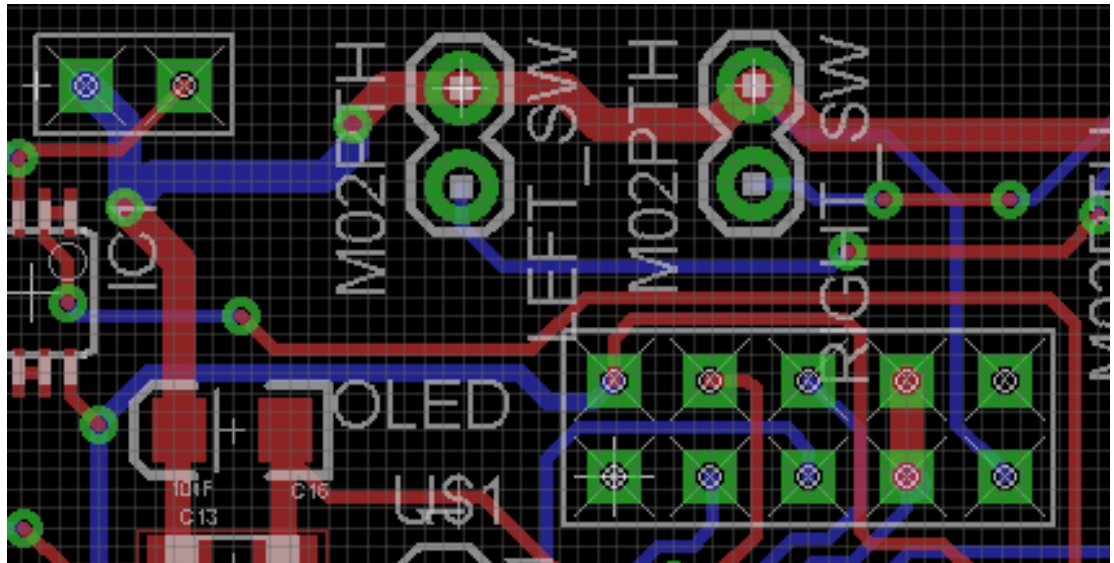
- Have unnecessary right angles been removed?
- Have PCB trace bends, loops, and spurs been removed?  
(Loops function like antennae at high frequencies)
- Has octagonal routing mode been used?  
("Anything-goes" diagonal routing mode is not recommended for designs)



# ROUTING CHECKS

## Via Minimization Check

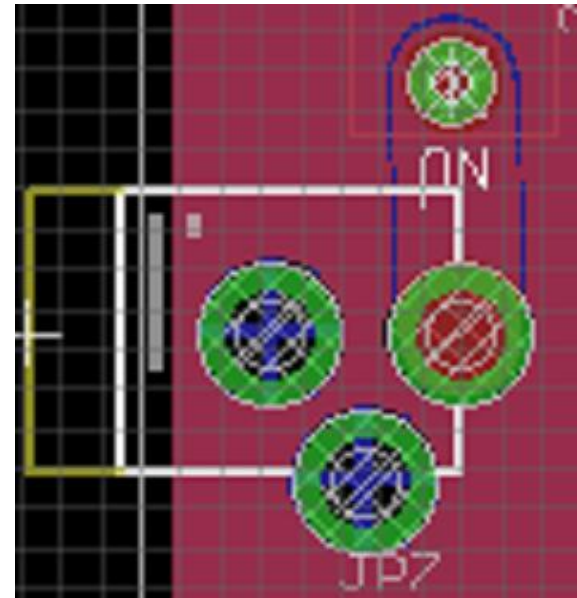
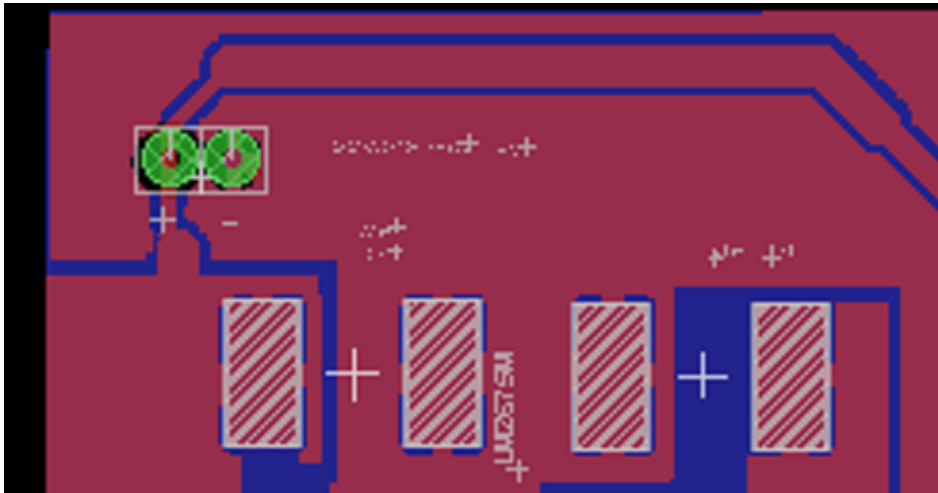
- Have unnecessary vias been removed?
- Remember: you can enter through-hole pins from either the top or bottom layers, just like vias
- Remember: you can route standard ~10 mil signal traces between pairs of 0.1" spaced through-holes without violating clearance requirements
- Remember: you can route into a pin/pad from any direction, including behind it



# ROUTING CHECKS

## Trace/Via Current Capacity Check

- Have traces been sized appropriately to the amount of current they are carrying? (32 mils or greater is recommended for power traces; consult trace width calculators for high current traces)
- Have vias in high-current traces been sized appropriately to match the trace width?



# SIGNAL PLANE CHECKS

- Are signal planes being used where appropriate?
- Has the isolation on all signal planes been set to an appropriate value? (Eagle currently defaults isolation to 0; signal plane isolation of 12 mils or greater is **STRONGLY** recommended).

The screenshot shows the 'Properties' dialog box in Eagle, which is used for configuring various elements in a PCB layout. The dialog is divided into three main sections: Wire, Polygon, and Signal.

**Wire Section:**

- From:** 2559.05512
- To:** 0
- Length:** 2559.05512
- Angle:** 180
- Width:** 12 (dropdown menu)
- Cap:** round (dropdown menu)
- Layer:** 16 Bottom (dropdown menu)
- Curve:** 0

**Polygon Section:**

- Polygon Pour:** solid (dropdown menu)
- Spacing:** 50 (dropdown menu)
- Isolate:** 12 (dropdown menu)
- Rank:** 1 (dropdown menu)
- ☐ Orphans
- ☒ Thermals

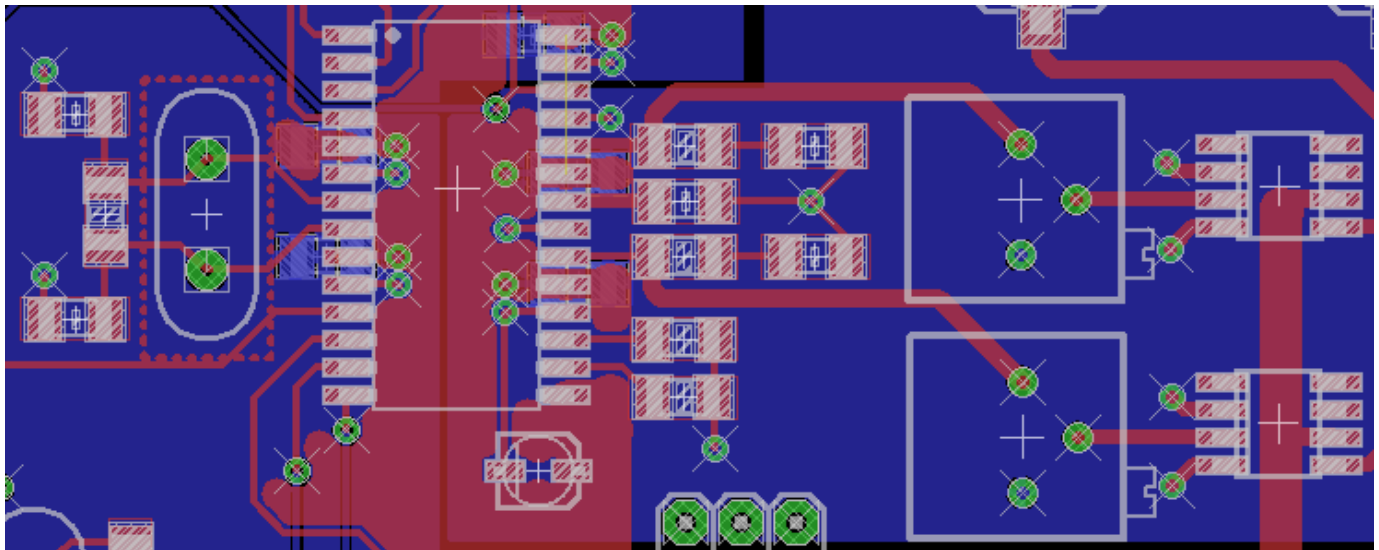
**Signal Section:**

- Name:** GND
- Net Class:** 0 default (dropdown menu)
- ☐ Airwires hidden

At the bottom of the dialog are three buttons: OK, Cancel, and Apply.

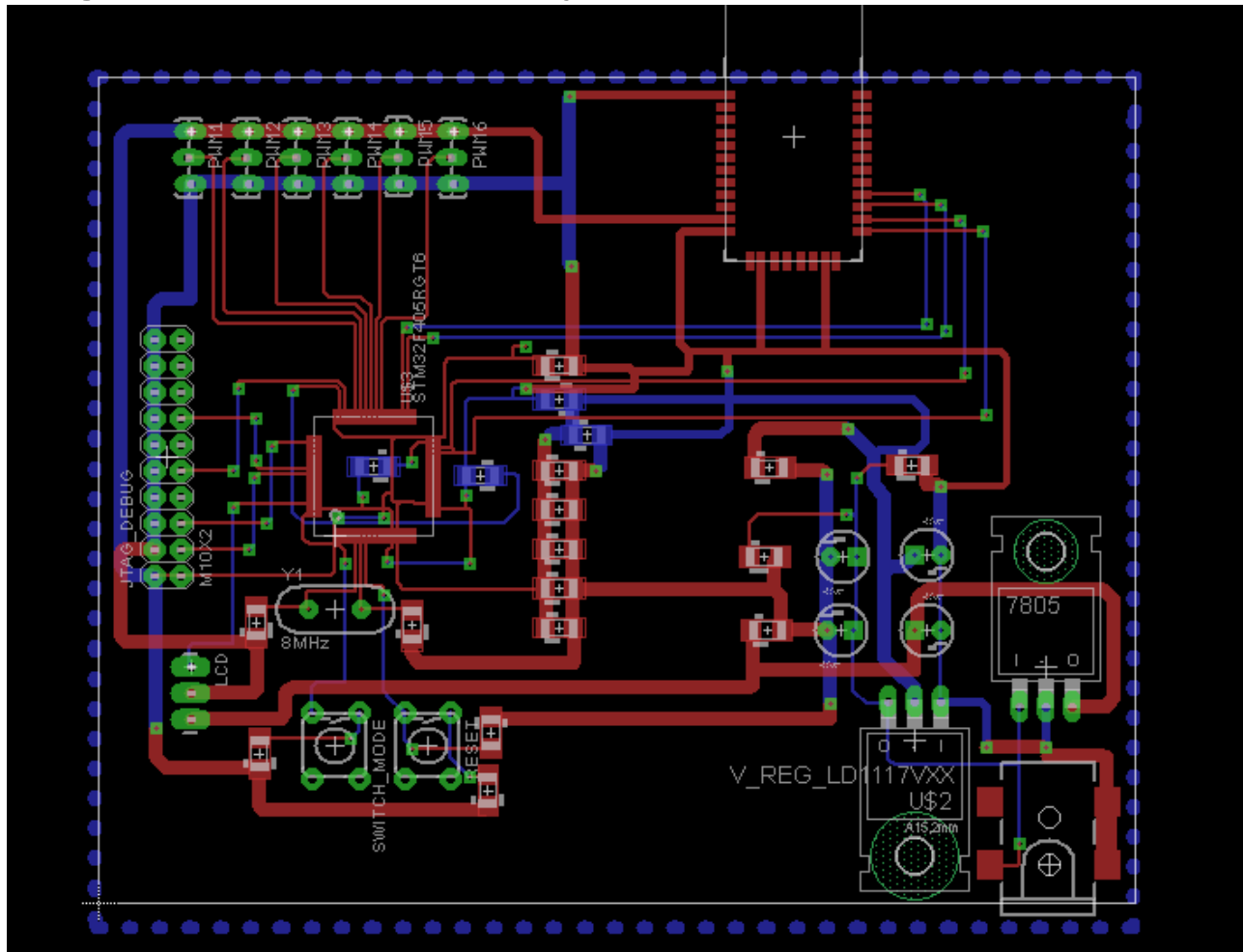
# SILKSCREEN CHECKS

- Have labels been provided (in either the name or silkscreen layers) for all component IDs and appropriate connector signal names?
- Is pin 1 of all polarity-sensitive ICs and passives clearly marked?
- Have all silkscreen labels been positioned so as to not overlap pins, pads, or anywhere else that solder will be applied?



# PCB LAYOUT IMPROVEMENTS

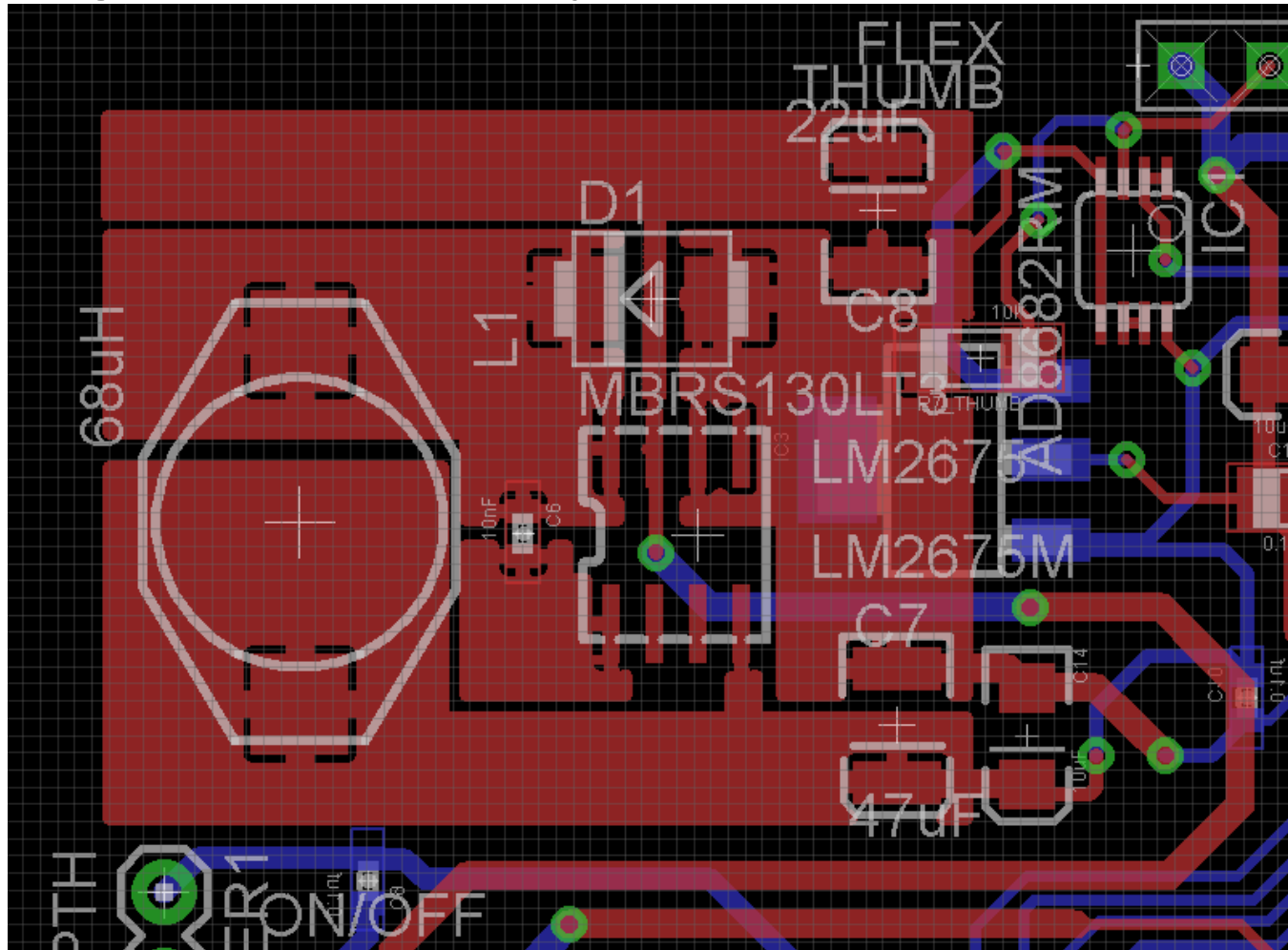
- What's good about this layout? What could be improved?





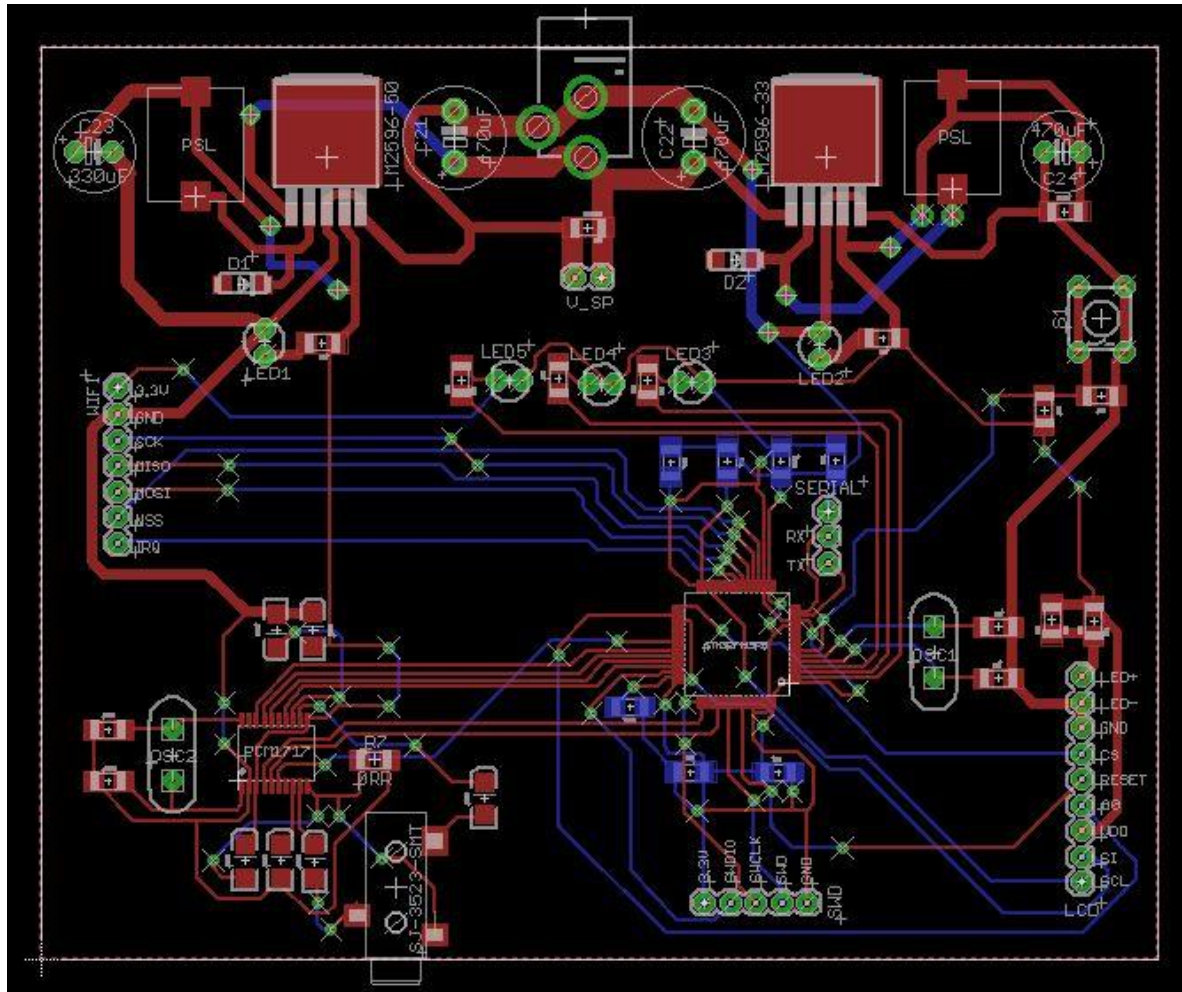
# PCB LAYOUT IMPROVEMENTS

- What's good about this layout? What could be improved?



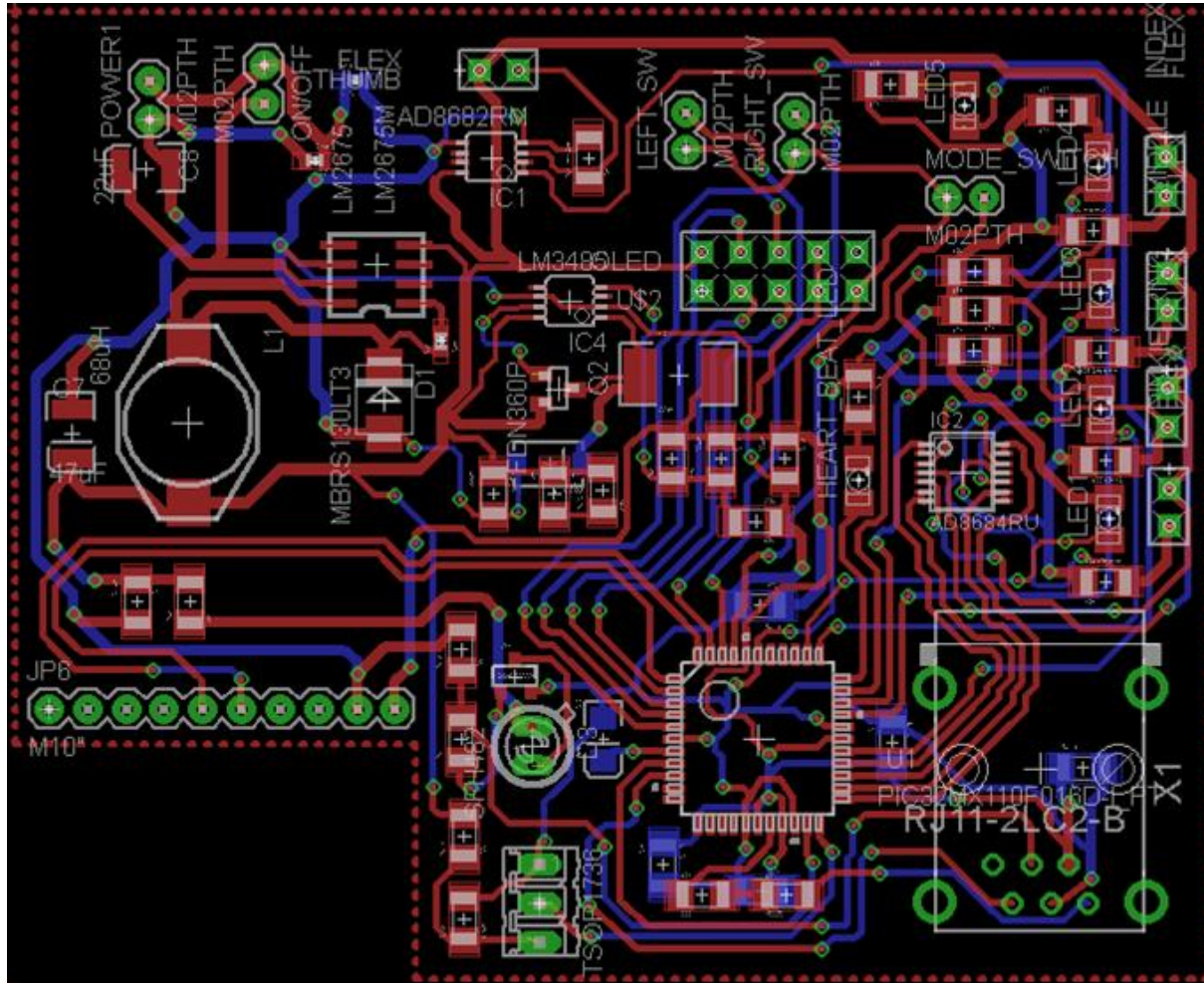
# PCB LAYOUT IMPROVEMENTS

- What's good about this layout? What could be improved?



# PCB LAYOUT IMPROVEMENTS

- What's good about this layout? What could be improved?



- What's good about this layout? What could be improved?



# GERBER FILE GENERATION

- Once PCB has been routed and passes DRC + verification checks, the design must be translated into machine files for PCB fabhouse equipment
- The current industry standard for PCB fabrication is the Gerber RS274-X format (output option for Eagle, Altium, etc.)
- In Eagle, CAM processor files are available on the course website  
(<https://engineering.purdue.edu/ece477/Course/Process/process.html>)



# GERBER FILE GENERATION

- The CAM processor outputs a number of Gerber files:
  - \*.GTO (Top Overlay): Top silkscreen
  - \*.GTS (Top Soldermask): Top soldermask
  - \*.GTL (Top Layer): Top copper
  - \*.GBL (Bottom Layer): Bottom copper
  - \*.GBS (Bottom Soldermask): Bottom soldermask
  - \*.GBO (Bottom Overlay): Bottom silkscreen
  - \*.XLN (Excellon): Drill holes
- Once generated, inspect files with Gerber viewer (gerbv recommended). When satisfied, zip files and send to fabhouse

# PCB ORDERING



- A few useful resources:
  - [OSH Park](#): US-based hobbyist service. \$5/square inch, 3 copies of each board design
  - [Advanced Circuits](#): US-based. \$33 student board special, quick turn times
  - [PCBShopper](#): PCB marketplace to compare price quotes from 26 manufacturers instantly



# Questions?